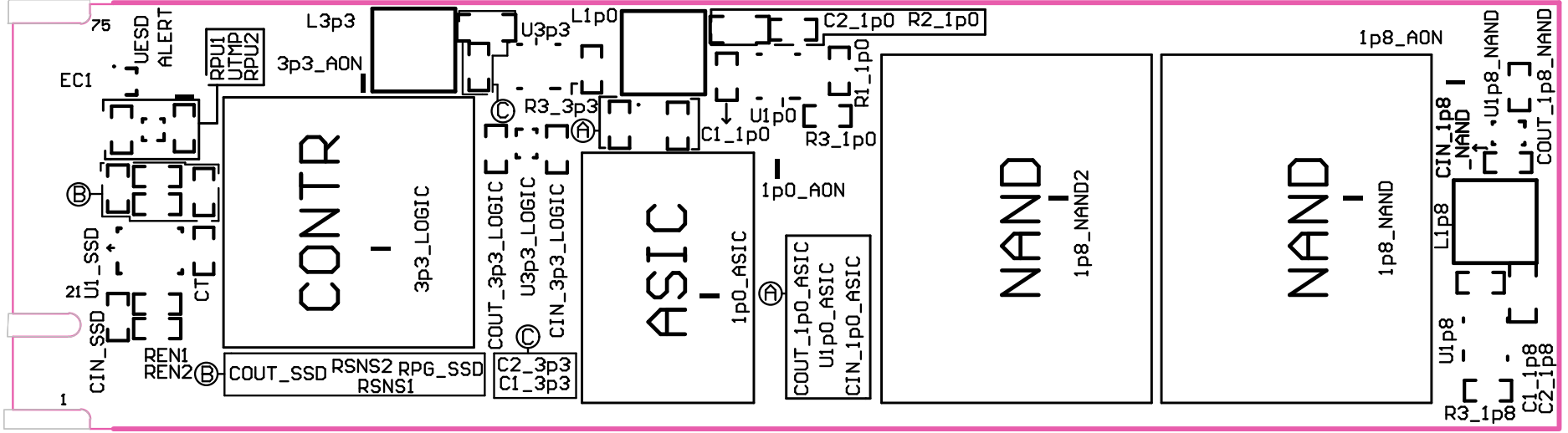
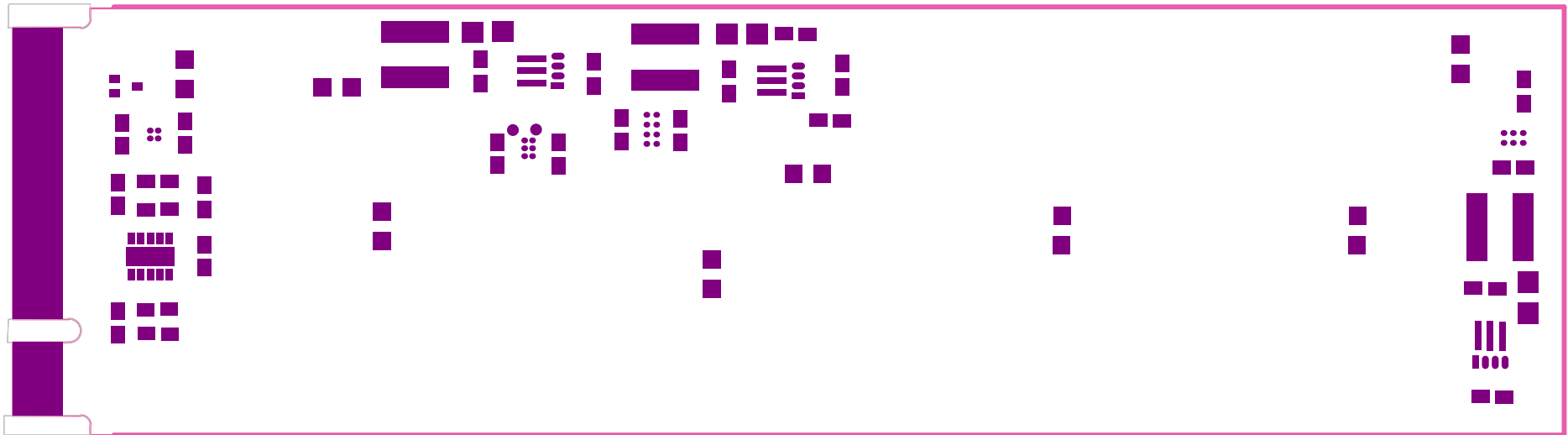


Top Overlay

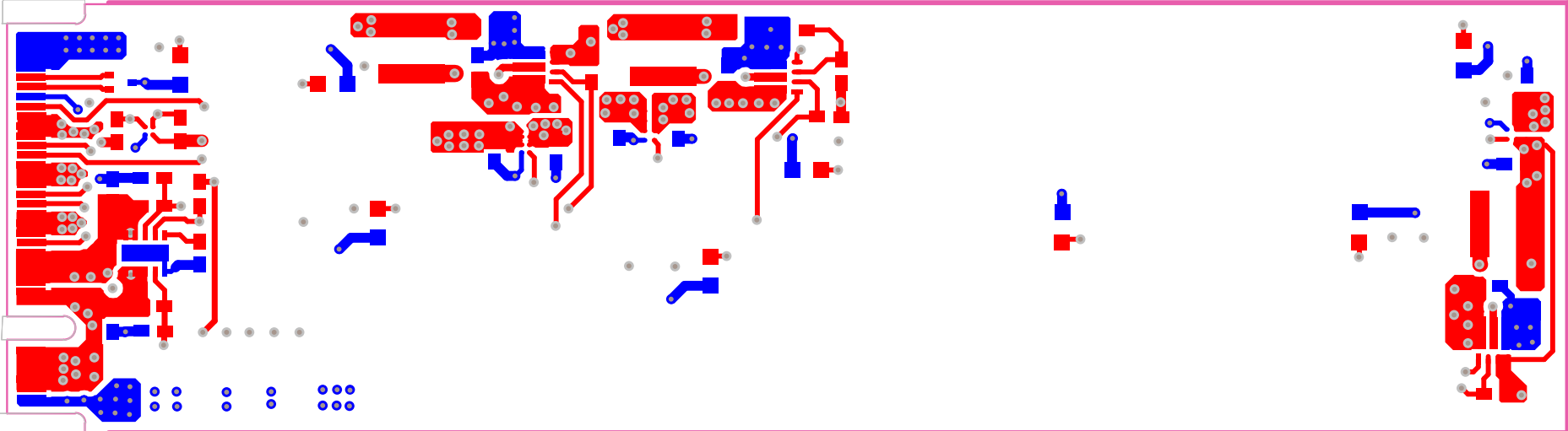


CIN_1p8_NAND

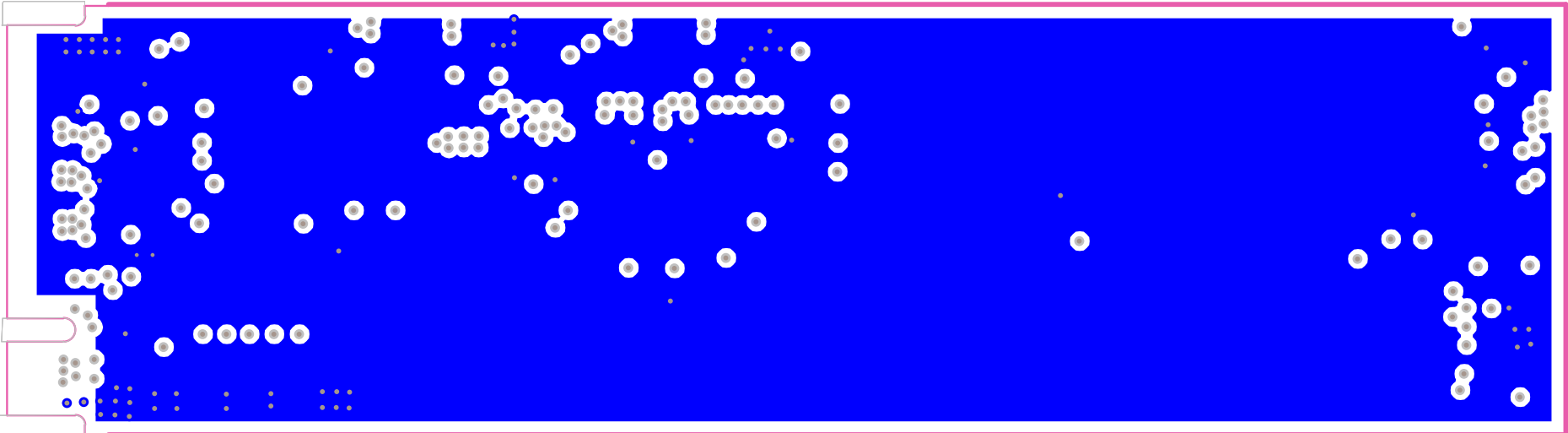
Top Solder



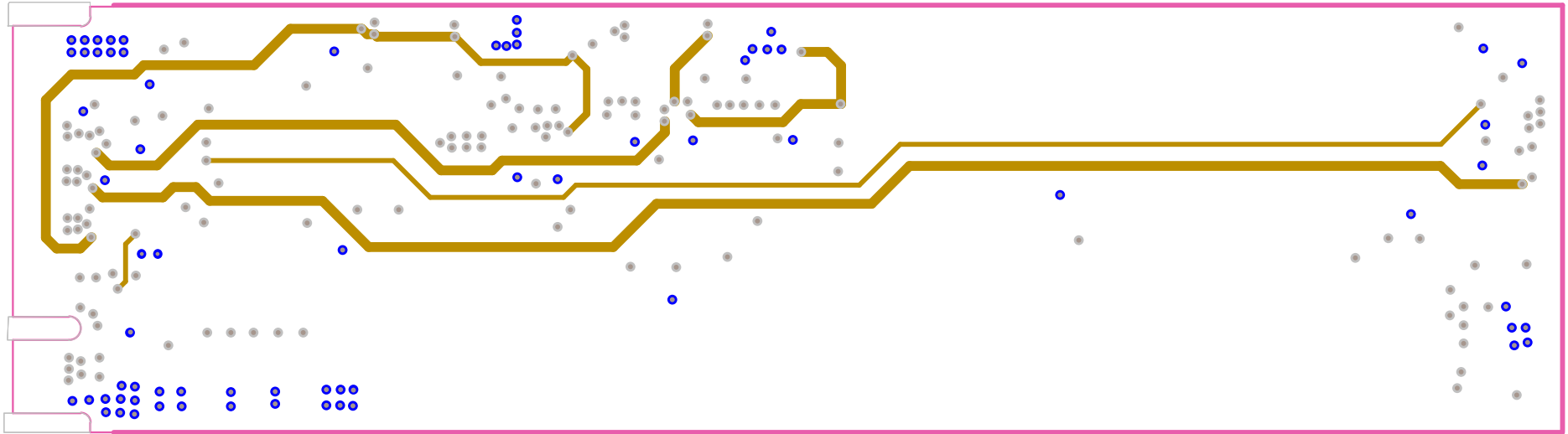
01_Top Layer



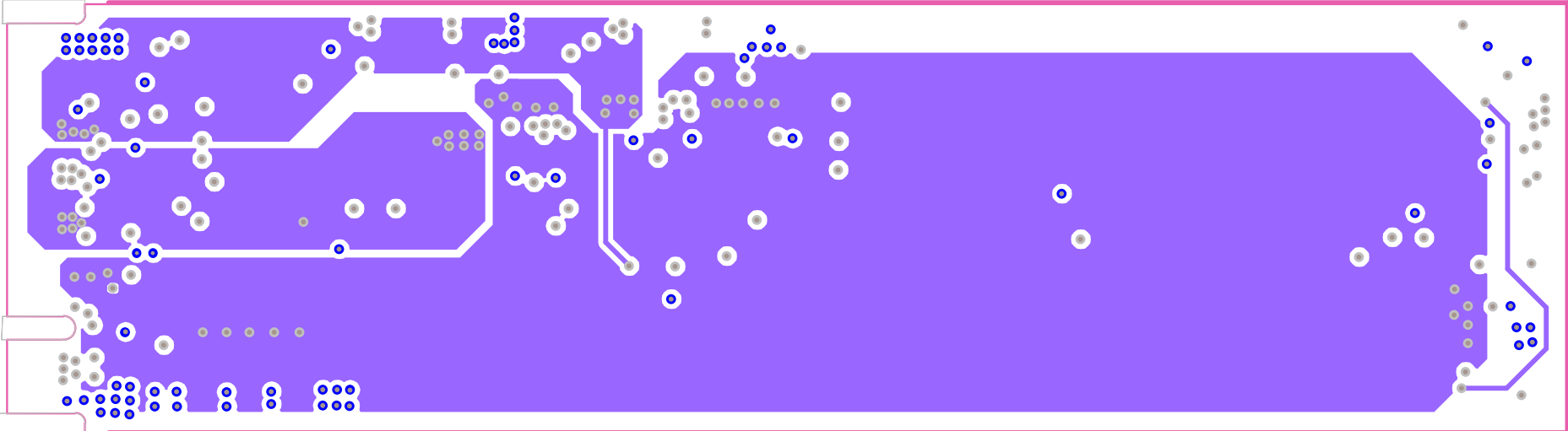
02_GND_01



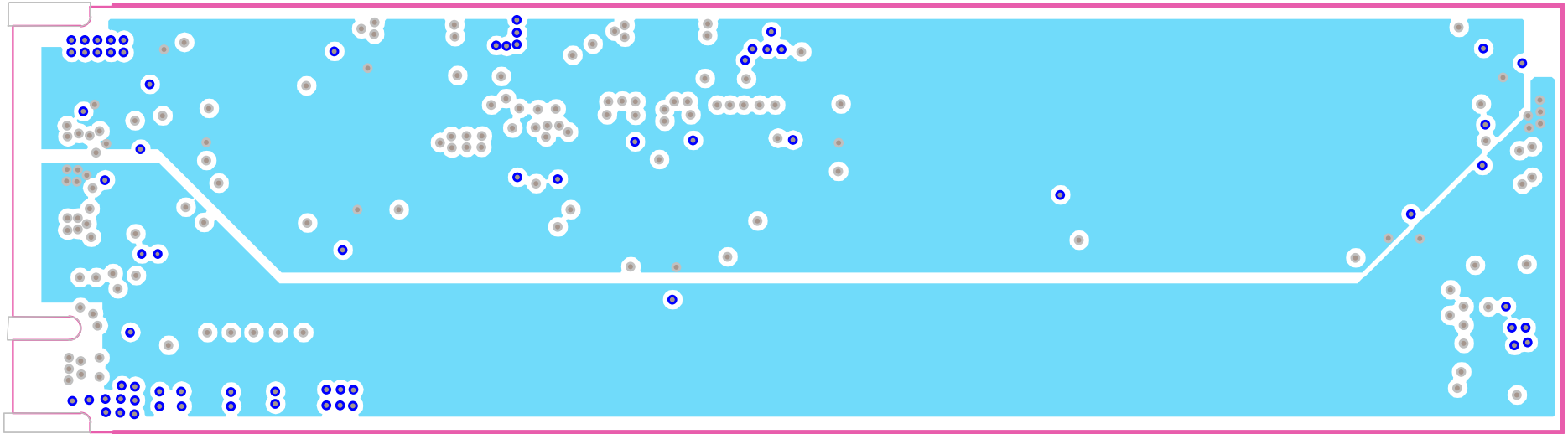
03_PWR_01



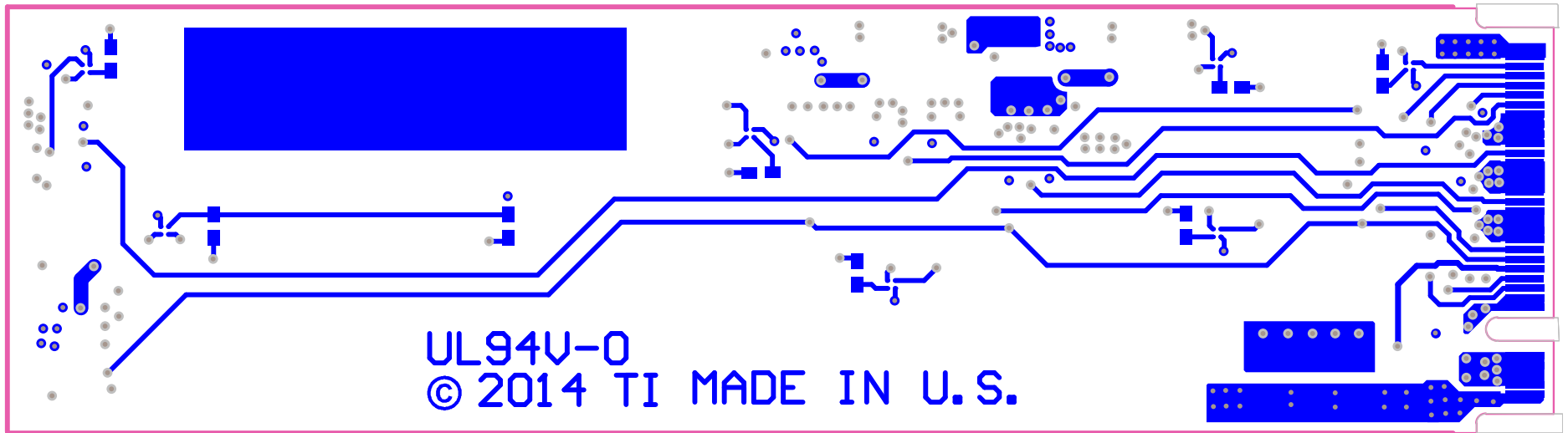
04_PWR_02



05_PWR_03



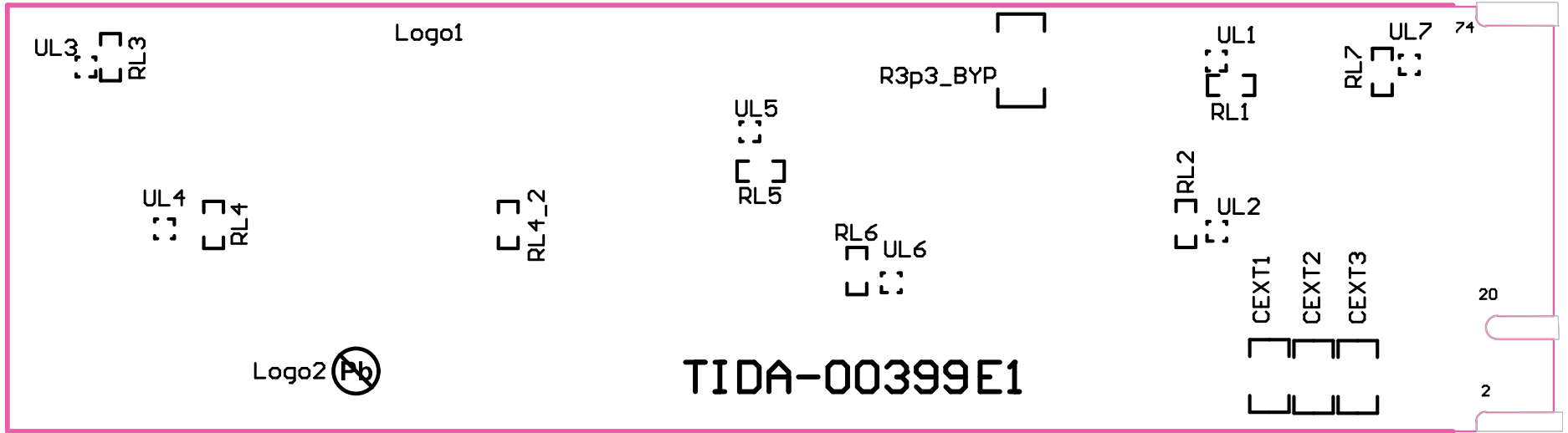
06_Bottom Layer



Bottom Solder



Bottom Overlay



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